

F-5202

Conductive Form-In-Place Gasket

Characteristics:

The F-5202 is an Ag/Cu filled moisture curable silicone with very good electrical conductivity.

It is a one component, moisture (room) curable Silicone system, optimized for Form-In-Place process. It is ideally suitable for Metal or Metallized (Vapor Deposition) Glass Fiber filled Plastic substrates.

Applications:

- Base Station
- Telecommunication Devices
- Mobile phone

Typical Properties:

Properties	Unite	F-5202
Elastomer Binder		Silicone
Conductive Filler		Ag/Cu
Physical Properties		
Specific Gravity	g/cm	2.4
Shore A Hardness		62
	psi	150
	%	> 35
	lb/in	40
Compression Set	%	30
Color		Silver color
Temperature Range	°C	-55 ~+125
	°C	150
Electrical Properties		
Volume Resistivity	Ohm .cm	0.08
H-Field, 10 KHz	dB	
	dB	
	dB	

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